

Appl. No. 09/394,918  
Amendment dated: June 20, 2006  
Reply to OA of: March 20, 2006

This listing of claims will replace all prior versions and listings of claims in the application.

**Listing of Claims:**

Claims 1-6(Canceled).

7(Currently Amended). A process for sawing a substrate strip having a plurality of substrate areas by a saw machine, and the process comprising the steps of:

providing a plurality of alignment marks around each individual substrate area on the substrate strip;

providing a plurality of cutting marks around each individual substrate area on the substrate strip;

positioning the saw machine with respect to each individual substrate area in accordance with the alignment marks there around;

cutting each individual substrate area on the substrate strip by the saw machine respectively according to cutting tracks defined by the cutting marks;

wherein the substrate strip has a longitudinal axis and a lateral axis and the substrate areas are disposed along the longitudinal axis, the saw machine is positioned with respect to a first substrate area according to the alignment marks along the longitudinal axial from one side thereof and cuts the substrate strip according to cutting tracks defined by the cutting marks parallel to the lateral axis;

repositioning the saw machine with respect to an adjacent one of the substrate areas after the substrate strip undergoes shrinkage; and

cutting the substrate strip, wherein cutting error that results from each substrate area will not accumulate to the subsequent substrate areas in the substrate strip.

Claim 8(Canceled).

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9(Previously Presented). The process as claimed in claim 7, further comprising the step of cutting the substrate strip according to cutting tracks defined by the cutting marks parallel to the longitudinal axis.

10(Previously Presented). The process as claimed in claim 7, wherein each individual substrate area is provided with at least three alignment marks.

11(Previously Presented). The process as claimed in claim 7, further comprising an encapsulated area on each individual substrate area, and the encapsulated area is provided with at least three alignment marks there around.

12(Previously Presented). The process as claimed in claim 7, wherein two substrate strips are juxtaposed for cutting simultaneously.

Claim 13(Canceled).

14(Currently Amended). A process for sawing a substrate strip having a plurality of substrate areas by a saw machine, comprising:

providing a substrate strip including a longitudinal axis and a lateral axis, a plurality of substrate areas being aligned along the longitudinal axis at regular intervals on the substrate strip;

providing a plurality of alignment marks corresponding to each individual substrate area on the substrate strip;

providing a plurality of cutting marks corresponding to each individual substrate area on the substrate strip in accordance with said plurality of alignment marks;

positioning a saw along the longitudinal axis of an individual substrate area in accordance with the alignment marks there provided ;

cutting said individual substrate area parallel to the lateral axis using the saw in accordance with cutting tracks defined by the cutting marks;

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repositioning the saw with respect to at least one subsequent individual substrate area after the substrate strip undergoes shrinkage; and

cutting said subsequent individual substrate area on the substrate strip, wherein cutting error being generated from each individual substrate area, due to previous variable shrinkage of the substrate strip and less than a predetermined value, failing to accumulate to the subsequent substrate areas in the substrate strip.

15(new). The process as claimed in claim 7, wherein the alignment marks are formed at the corners of each substrate area on the substrate strip.

16(new). The process as claimed in claim 14, wherein the alignment marks are formed at the corners of each substrate area on the substrate strip.